

L Number	Hits	Search Text	DB	Time stamp
11	13114	((multichip adj module) (multi adj chip adj module) mcm)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/10 08:25
12	3121	((multichip adj module) (multi adj chip adj module) mcm)) and memory	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/10 08:26
13	979	((multichip adj module) (multi adj chip adj module) mcm)) and (second near1 (chip die semiconductor))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/10 08:28
14	910	((multichip adj module) (multi adj chip adj module) mcm)) and (second near1 (chip die semiconductor))) and (method process)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/10 09:32
15	3547	(second near1 (chip die semiconductor)) near3 (electrode ((bond bonding) ajd pad))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/10 09:33
16	284	((multichip adj module) (multi adj chip adj module) mcm)) and ((second near1 (chip die semiconductor)) near3 (electrode ((bond bonding) ajd pad)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/10 08:30
17	273	((multichip adj module) (multi adj chip adj module) mcm)) and ((second near1 (chip die semiconductor)) near3 (electrode ((bond bonding) ajd pad)))) and (method process)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/10 09:22
18	258	((multichip adj module) (multi adj chip adj module) mcm)) and ((second near1 (chip die semiconductor)) near3 (electrode ((bond bonding) ajd pad)))) and (method process)) and (wiring wire)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/10 09:23
20	2	"6452266"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/10 08:41
21	3	"6388318"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/10 08:41
22	3	"6452266" "6388318"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/10 08:41
23	3	("5691570" "5966630" "6121681").PN.	USPAT	2003/02/10 08:41
19	251	((multichip adj module) (multi adj chip adj module) mcm)) and ((second near1 (chip die semiconductor)) near3 (electrode ((bond bonding) ajd pad)))) and (method process)) and (wiring wire)) and (substrate pcb (printed adj circuit adj board))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/10 08:43
24	10	("5172303" "5237204" "5748452" "5784264" "5864062" "5963430" "6201294" "6297548" "6313522" "6316727").PN.	USPAT	2003/02/10 08:48
25	5	5784264.URPN.	USPAT	2003/02/10 08:49
26	2	("4882657" "5438224").PN.	USPAT	2003/02/10 08:49
27	4	("5715144" "5854507" "6025648" "6093969").PN.	USPAT	2003/02/10 08:59
28	4	6014586.URPN.	USPAT	2003/02/10 09:03
29	8	("4467400" "4614194" "5291061" "5835396" "6014586" "6205082" "6272069" "6291836").PN.	USPAT	2003/02/10 09:04
30	82	4467400.URPN.	USPAT	2003/02/10 09:05
31	5	5612575.URPN.	USPAT	2003/02/10 09:08

32	2820	((second near1 (chip die semiconductor)) near3 (electrode ((bond bonding) ajd pad))) and (method process)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/10 09:23
33	1672	((second near1 (chip die semiconductor)) near3 (electrode ((bond bonding) ajd pad))) and (method process)) and (wiring wire)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/10 09:24
34	217	((second near1 (chip die semiconductor)) near3 (electrode ((bond bonding) ajd pad))) and (method process)) and (wiring wire)) and (bga (ball adj grid adj array))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/10 09:33
35	132	((second near1 (chip die semiconductor)) near3 (electrode ((bond bonding) ajd pad))) and (method process)) and (wiring wire)) and (bga (ball adj grid adj array)) not (((multichip adj module) (multi adj chip adj module) mcm)) and ((second near1 (chip die semiconductor)) near3 (electrode ((bond bonding) ajd pad))) and (method process)) and (wiring wire)) and (substrate pcb (printed adj circuit adj board)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/10 09:25
36	2884	((multichip adj module) (multi adj chip adj module) mcm)) and memory) and (method process)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/10 09:32
37	1431	((multichip adj module) (multi adj chip adj module) mcm)) and memory) and (method process)) and (electrode ((bond bonding) ajd pad)) and (wiring wire)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/10 09:34
38	367	((multichip adj module) (multi adj chip adj module) mcm)) and memory) and (method process)) and (electrode ((bond bonding) ajd pad)) and (wiring wire)) and (bga (ball adj grid adj array))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/10 09:34
39	367	((multichip adj module) (multi adj chip adj module) mcm)) and memory) and (method process)) and (electrode ((bond bonding) ajd pad)) and (wiring wire)) and (bga (ball adj grid adj array)) and (chip die)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/10 09:35
40	310	((multichip adj module) (multi adj chip adj module) mcm)) and memory) and (method process)) and (electrode ((bond bonding) ajd pad)) and (wiring wire)) and (bga (ball adj grid adj array)) and (chip die)) not (((multichip adj module) (multi adj chip adj module) mcm)) and ((second near1 (chip die semiconductor)) near3 (electrode ((bond bonding) ajd pad))) and (method process)) and (wiring wire)) and (substrate pcb (printed adj circuit adj board)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/10 09:35

41	70	("1750369" "3387365" "3614540" "3631299" "3915307" "3930644" "3961413" "3982317" "4100675" "4109379" "4155447" "4198024" "4217624" "4219926" "4252864" "4291867" "4316320" "4343083" "4426773" "4480150" "4498120" "4554404" "4554613" "4567643" "4600231" "4663650" "4667403" "4720034" "4763782" "4805316" "4908738" "4910866" "4948108" "5016139" "5031074" "5044615" "5066614" "5067648" "5111935" "5148962" "5157590" "5208734" "5339221" "5366933" "5375040" "5406454" "5406455" "5456402" "5496535" "5501436" "5535509" "5563772" "5620927" "5620928" "5637916" "5661086" "5727311" "5732465" "5802709" "5897334" "5911329" "5953216" "5960961" "5988619" "5990545" "5992649" "6001671" "6013946" "6049972" "6158595").PN.	USPAT	2003/02/10 09:40
42	4	("4344064" "5280193" "5754410" "6117693").PN.	USPAT	2003/02/10 09:43
43	5	("5285352" "5331235" "5681777" "5910685" "5945741").PN.	USPAT	2003/02/10 09:44